
Survey of Total Ionizing Dose Tolerance

of power bipolar transistors and Silicon Carbide devices for JUICE

-Status of ongoing activities-

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2017-03-09

ESA & CNES Final Presentation Days: Radiation Effects on EEE components

Power bipolar transistors / SiC devices

Project details

- Project: „Survey of Total Ionizing Dose Tolerance of Power Bipolar Transistors and Silicon Carbide Devices for Juice“
- Contract 4000113976/15/NL/RA
- Price 225 k€
- Original timeframe: 18 months
- Start of project: 01.06.2015
- End of project: November 2017

Power bipolar / Silicon Carbide

Scope of the project

- Power Bipolar Transistors
 - Select and test six power bipolar transistors for ELDRS sensitivity up to 200 krad(Si)
 - Based on industry preferred parts
- SiC device
 - Evaluate TID hardness of commercially available SiC power devices
 - Target dose rate 1 Mrad(Si)
 - Investigate SEE sensitivity up to an LET of 60 MeV cm²/mg
 - SEE tests with protons to assess sensitivity for LET < 15 MeV cm²/mg
 - (SEE tests to be done, not covered in this presentation)

Part Selection

Power bipolar transistors

Component	Type	Package	V_{CE}	I_C	Lot/Date code
2ST21600 (STMicroelectronics)	PNP	SMD.22	-400 V	0.5 A	33528003ZT
2N7370 (Microsemi)	NPN	TO-254AA	100 V	12A	88115 / 1642 CDWR
2N7371 (Microsemi)	PNP	TO-254AA	-100 V	-12 A	1TWO086021 / 9D1633
BDS16 (Semelab)	NPN	TO-257AB	120 V	8 A	CM1438
BDS18 (Semelab)	PNP	TO-257AB	-120 V	-8 A	AF1615U
BUL54A (Semelab)	NPN	TO-257	500 V	4 A	KF1609Y

Part Selection

SiC power devices

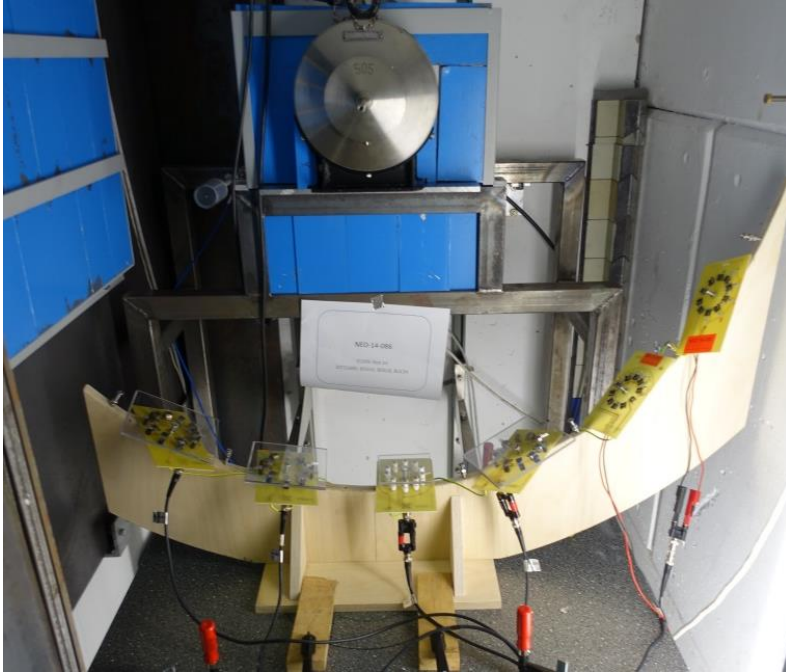
	Component	Pack.	V	I	Lot / Date code
MOSFET	C2M0080120D (Cree)	TO-247-3	V_{DS} 1200 V	I_D 36 A	W14315
	SCT20N120 (STM)	HIP247	V_{DS} 1200 V	I_D 20 A	GK 06NVY/CHN GK546
Schottky	IDW10G120C5B (Infineon)	TO-247	V_R 1200 V	I_F 5 A	D1012B5 / HAA527
	C4D40120D (Cree)	TO-247-3	V_R 1200 V	I_F 56.5 A	W13714
	SML020DH12 (Semelab)	TO-258AA	V_R 1200 V	I_F 20 A	HM14070
JFET	IJW120RT100T1 (Infineon)	TO-247	V_{DS} 1200 V	I_D 26 A	HAA547

Power bipolar / Silicon Carbide Procurement

- Procurement initiated 12/2015
- Power Bipolar Transistors
 - Traceability information was not provided for initially proposed Microsemi 2N5154
 - Replaced with STMicroelectronics 2ST21600
 - 08/16: Announcement of large procurement delay of 2 components marked start of ELDRS testing campaign (4/6 components)
 - 2 remaining components started with significant delay (10/16) and (02/17)
- SiC power devices
 - Commercial devices
 - Traceability information available

Test Definition

Co-60 Facilities



■ TK100 @ INT

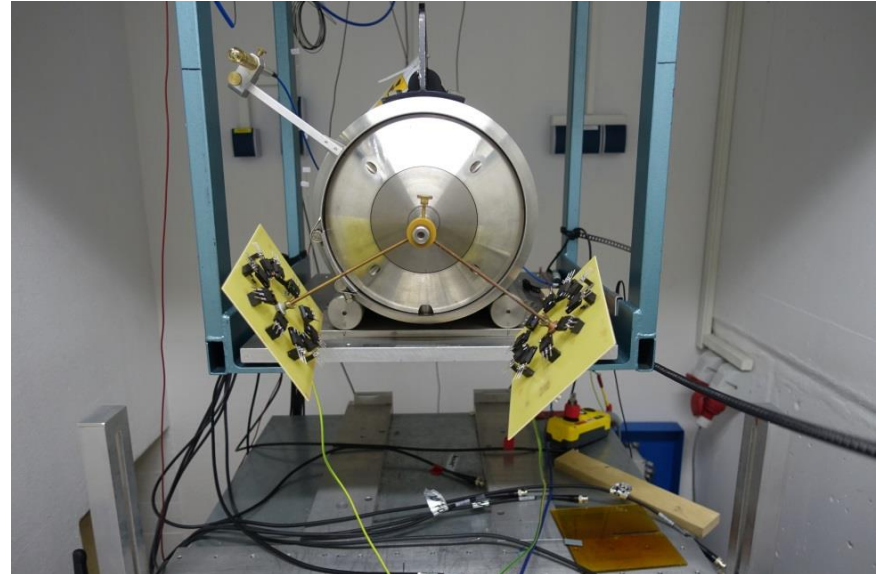
- ELDRS testing up to 200 krad(Si)
- Initial dose rate @ DUTs: ~35 rad/h
- Currently ~ 33 rad/h
- Ongoing since 08/2016
- Irradiation in fixed geometry
 - Dose rate reduction due to Co60-decay accounted for when calculating irradiation times

Test Definition

Co-60 Facilities

■ TK1000B @ INT

- High dose testing of PBT and SiC-devices
- Dose rate @ DUTs: 8.8 – 8.6 krad(Si)/h (multiple irradiations)
- SiC: Co60-Tests finished
 - 168h @ 100°C ongoing for 2 comp.
- PBT: High dose tests to be performed in the coming weeks



Test Definitions

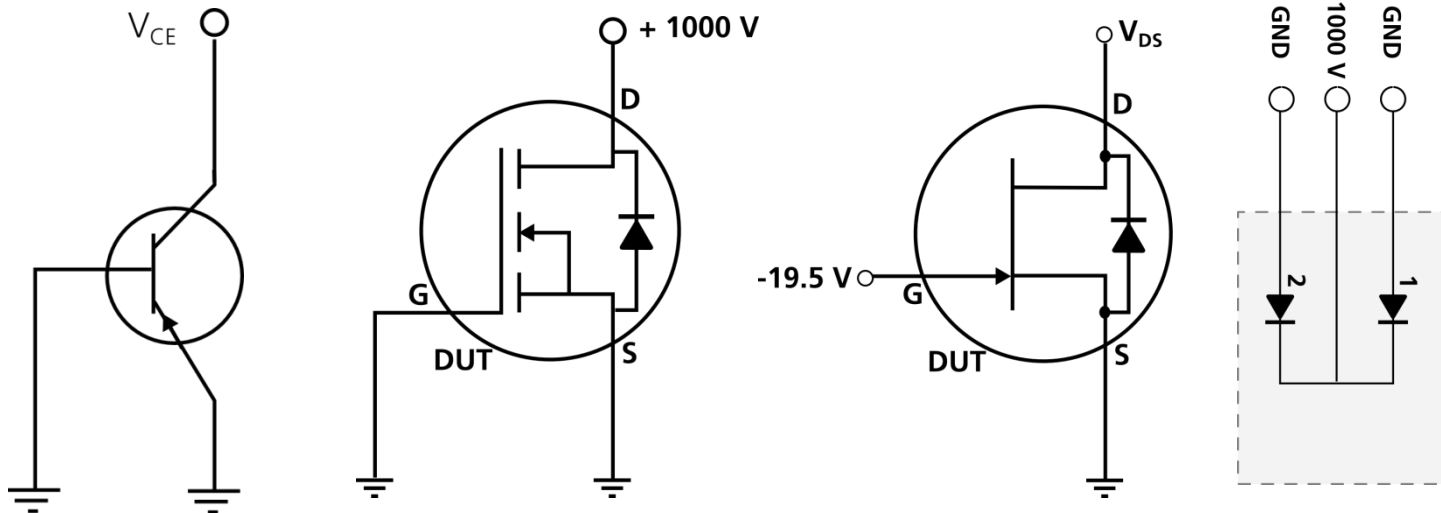
Test steps / Biasing

Power Bipolar Transistors

0 10 20 30 50 100 150 200 krad(Si)

Silicon Carbide Power Devices

0 30 50 100 300 500 1000 krad(Si)

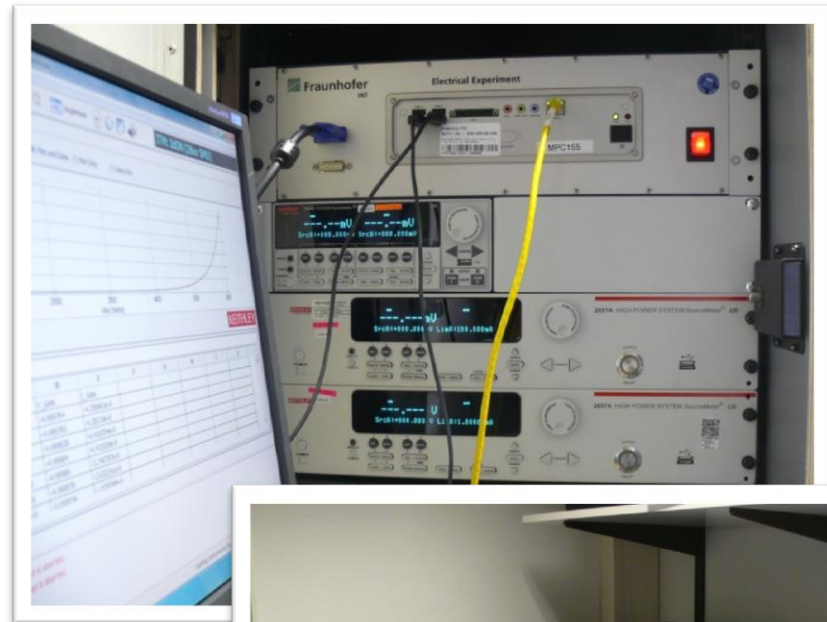


Test Definition

Test setup

■ Test setup

- High Power / High Voltage SMUs
 - Keithley 2657A (1.5 kV @ 120 mA)
 - Keithley 2651A (50 V @ 40 A pulsed)
 - Keithley 2636B (200 V @ 1 A pulsed)
- Synchronization of pulsed tests
- Keithley 8010 High Power Test Fixture



Test Definition

Power bipolar transistors

TM	Test	2ST21600	2N7370	2N7371	BDS16	BDS18	BUL54A
3001	Collector-Base Breakdown Voltage	X	--	--	--	--	X
3011	Collector Emitter Breakdown Voltage	X	X	X	X	X	X
3026	Emitter-Base Breakdown Voltage	X	--	--	--	--	X
3036	Collector-Base Cutoff Current	X	--	--	--	--	X
3041	Collector-Emitter Cut-Off Current	--	X	X	X	X	X
3061	Emitter-Base Cutoff Current	X	X	X	X	X	X
3066	Base-Emitter Saturation Voltage	X	X	X	X	X	X
3071	Collector-Emitter Saturation Voltage	X	X	X	X	X	X
3076	Forward Current Transfer Ratio	X	X	X	X	X	X

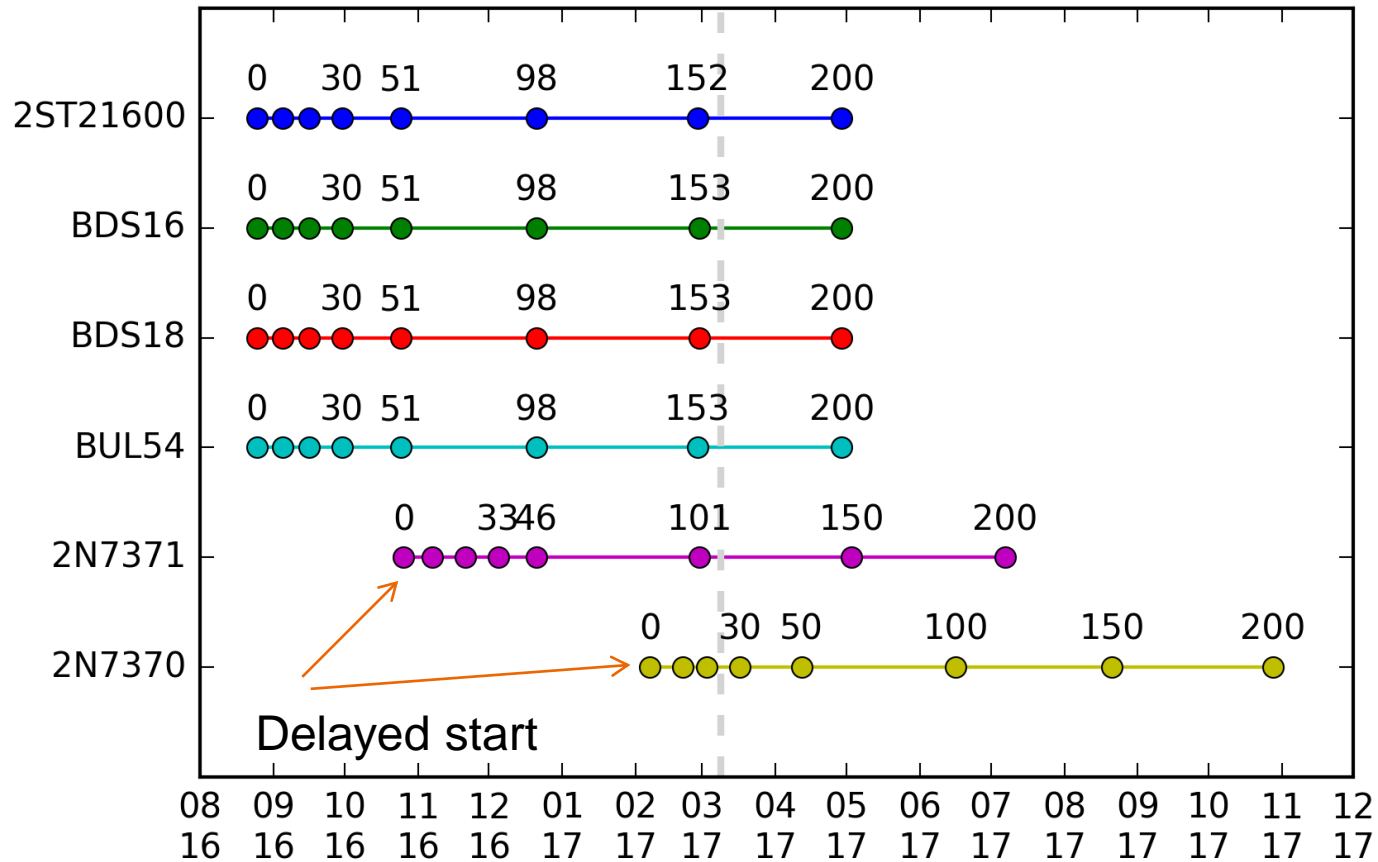
Test Definition

SiC Devices

TM	Test	MOSFET		JFET	Schottky		
		C2M0080120D	SCT20N120	IJW120R100T1	C4D40120D	IDW10G120C5B	SML020DH12
3407	Drain-Source Breakdown Voltage	X	X	X	--	--	--
3411	Gate-Source Leakage Current	X	X	X	--	--	--
3413	Zero Gate Voltage Drain Current	X	X	X	--	--	--
3403	Gate Threshold Voltage	X	X	X	--	--	--
3421	Drain-Source On-State Resistance	X	X	X	--	--	--
4011	Diode Forward Voltage	X	X	X	X	X	X
4016	Reverse Current	--	--	--	X	X	X

Power Bipolar Transistors

Current Status of ELDRS tests



Bipolar Power Transistors

Radiation levels (ongoing, ELDRS)

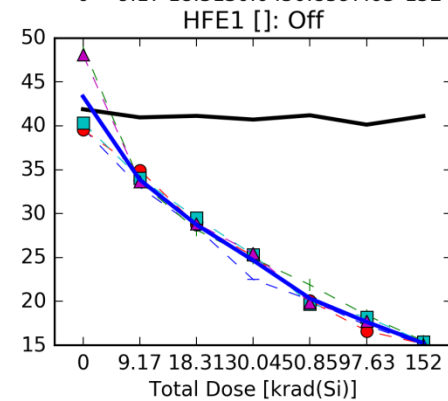
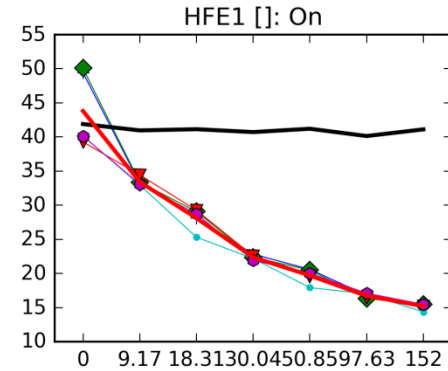
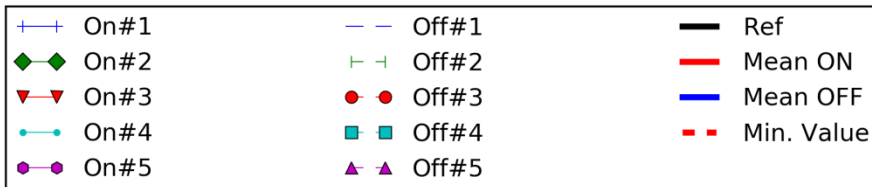
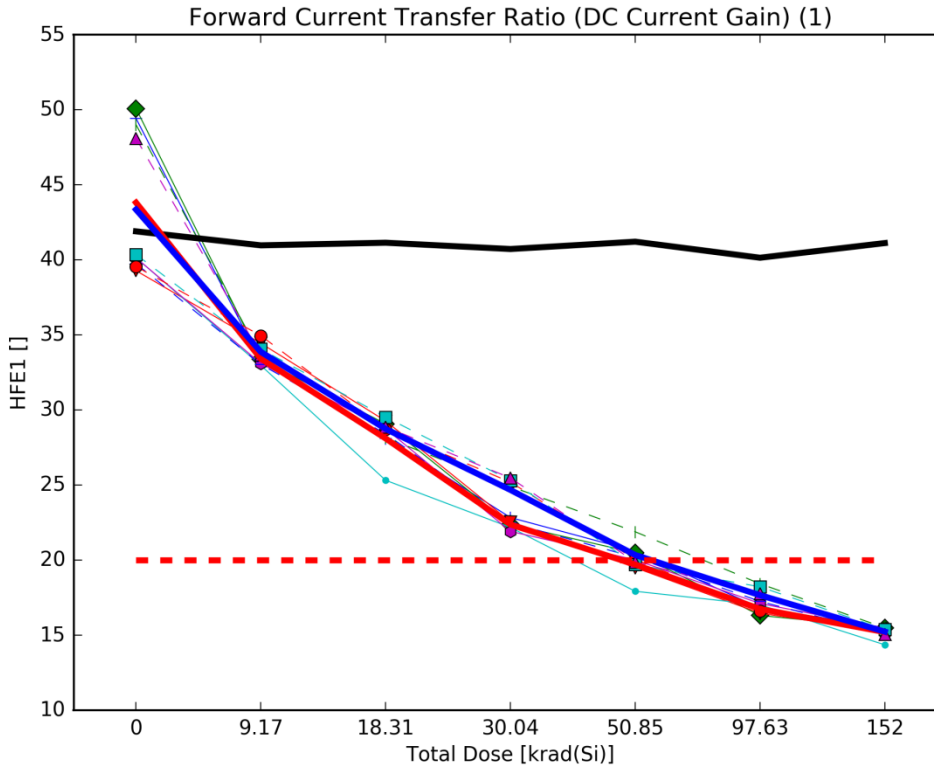
Radiation levels in krad(Si) (Test steps) at which parameters drift out of specs

TM	Test	2ST21600	2N7370	2N7371	BDS16	BDS18	BUL54A
3001	Collector-Base Breakdown Voltage	*					98
3011	Collector Emitter Breakdown Voltage	>150	>20	>100	>150	>150	>150
3026	Emitter-Base Breakdown Voltage	>150					>150
3036	Collector-Base Cutoff Current	*					18
3041	Collector-Emitter Cut-Off Current		>20	>100	>150	>150	>150
3061	Emitter-Base Cutoff Current	>150	>20	>100	>150	>150	>150
3066	Base-Emitter Saturation Voltage	>150	>20	>100	>150	>150	>150 >150
3071	Collector-Emitter Saturation Voltage	*	>20	>100	>150 >150	>150 >150	51 18 9
3076	Forward Current Transfer Ratio	*	>20	>100 >100	>150 >150	18 >150	51 30 >150

* Parameters out of specifications were observed, but influence of the setup on the results have to be reviewed, to be confirmed by HDR tests

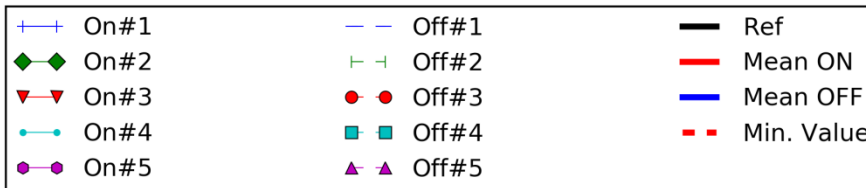
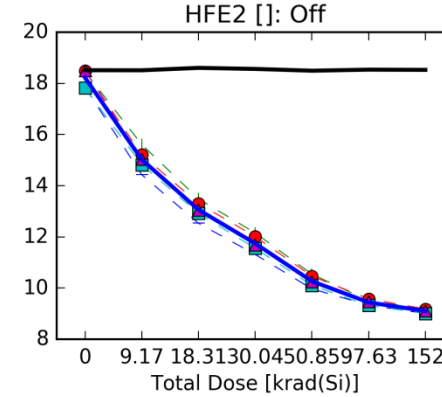
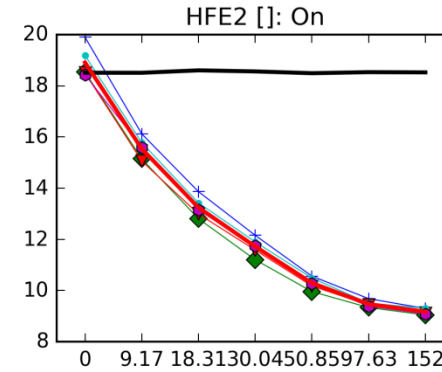
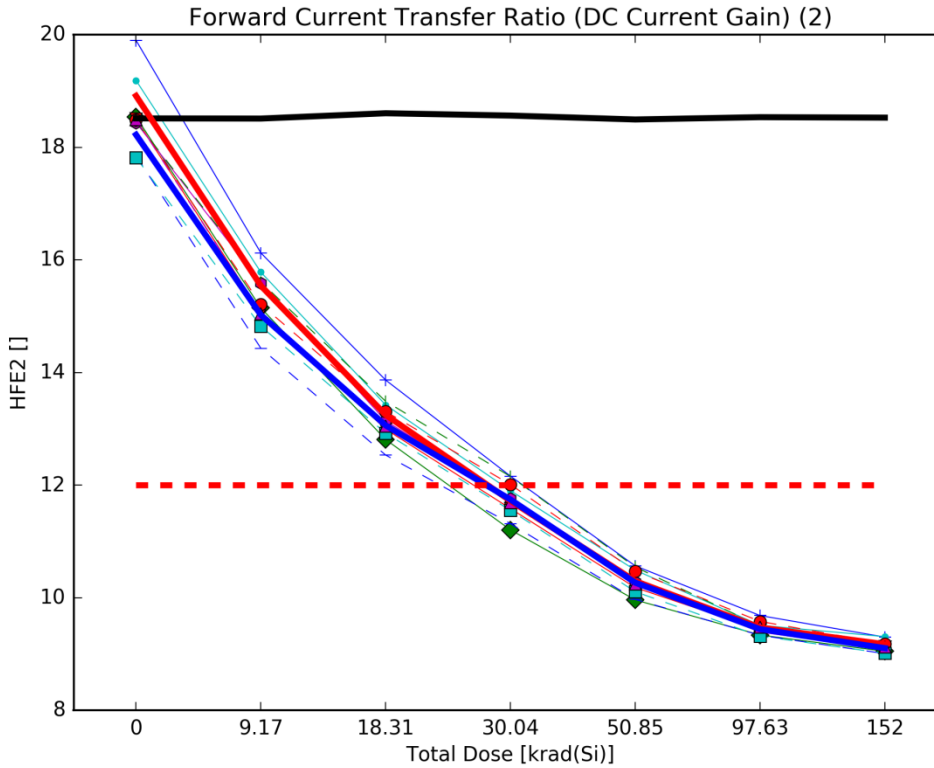
Current transfer ratio (HFE)

BUL54 #1: $V_{CE} = 5V, I_C = 0.1 A$



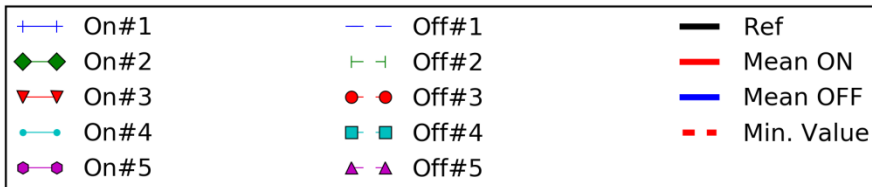
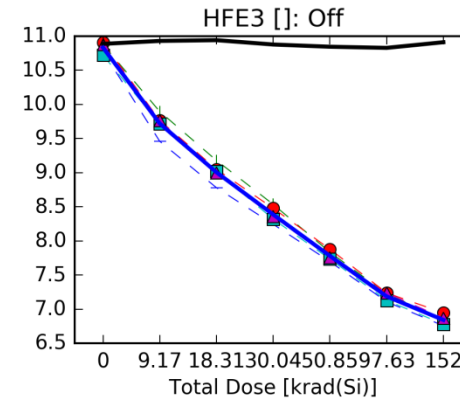
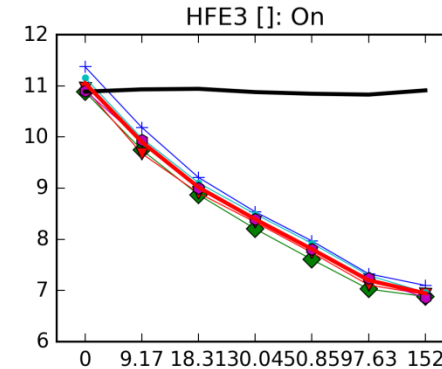
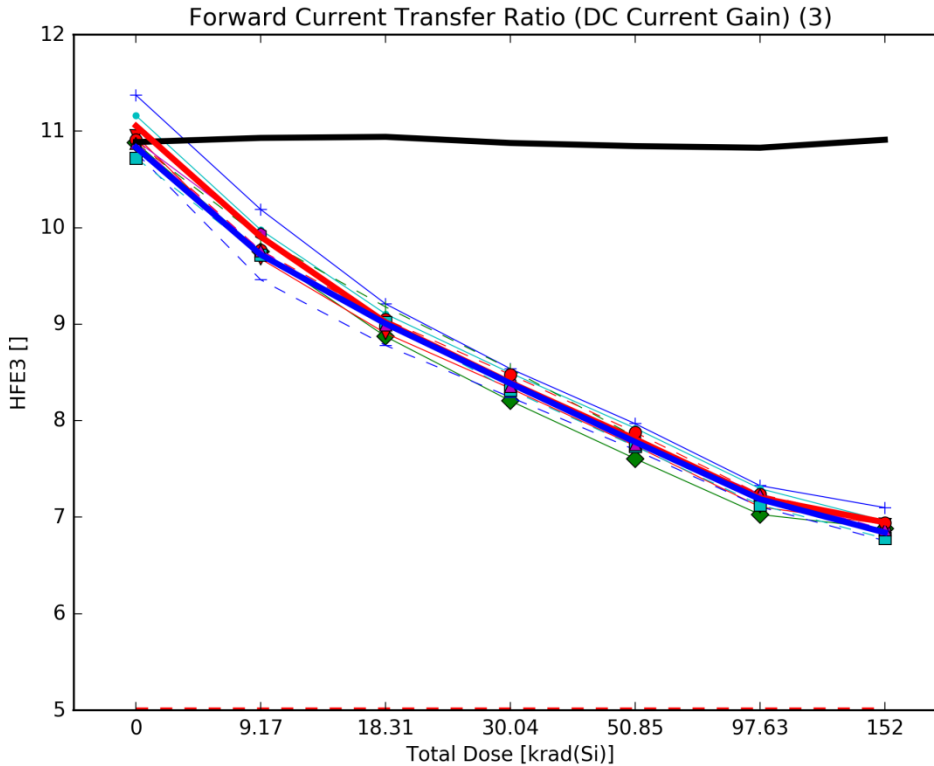
Current transfer ratio (HFE)

BUL54 #2: $V_{CE} = 5V, I_C = 0.5 A$



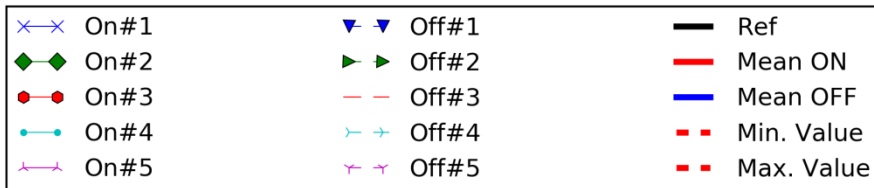
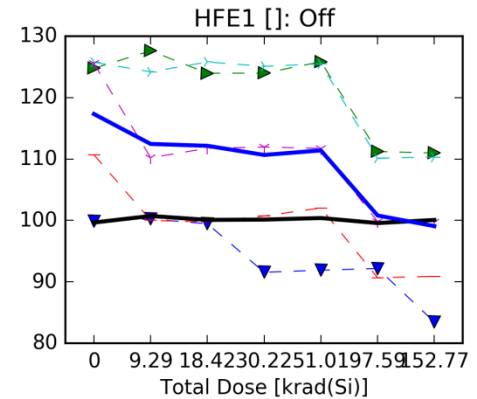
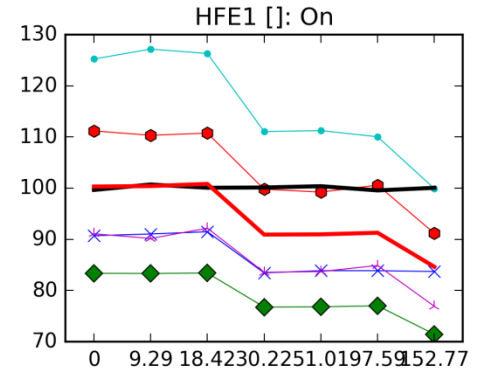
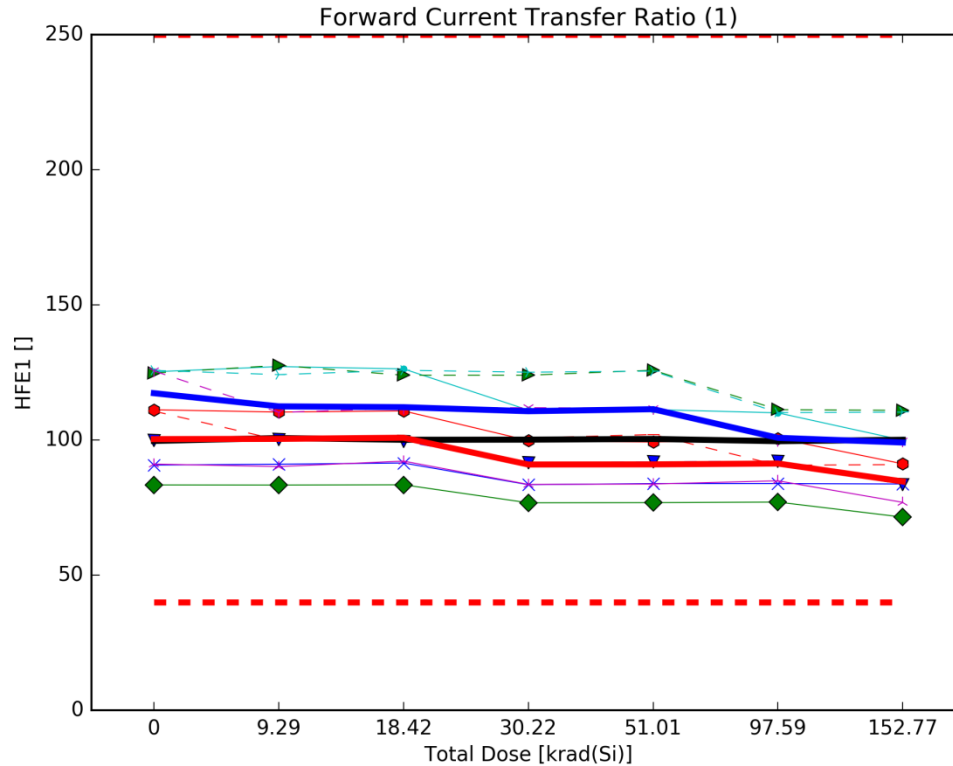
Current transfer ratio (HFE)

BUL54 #2: $V_{CE} = 5V, I_C = 1.0 A$



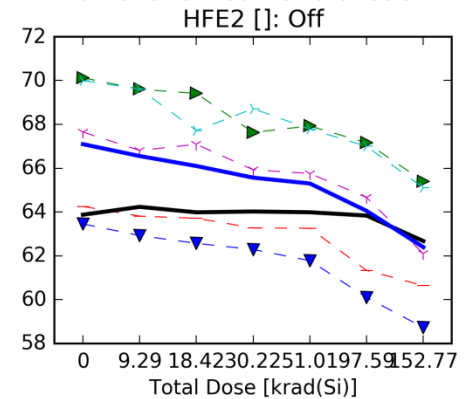
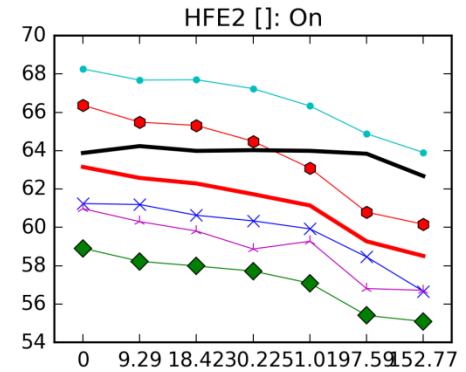
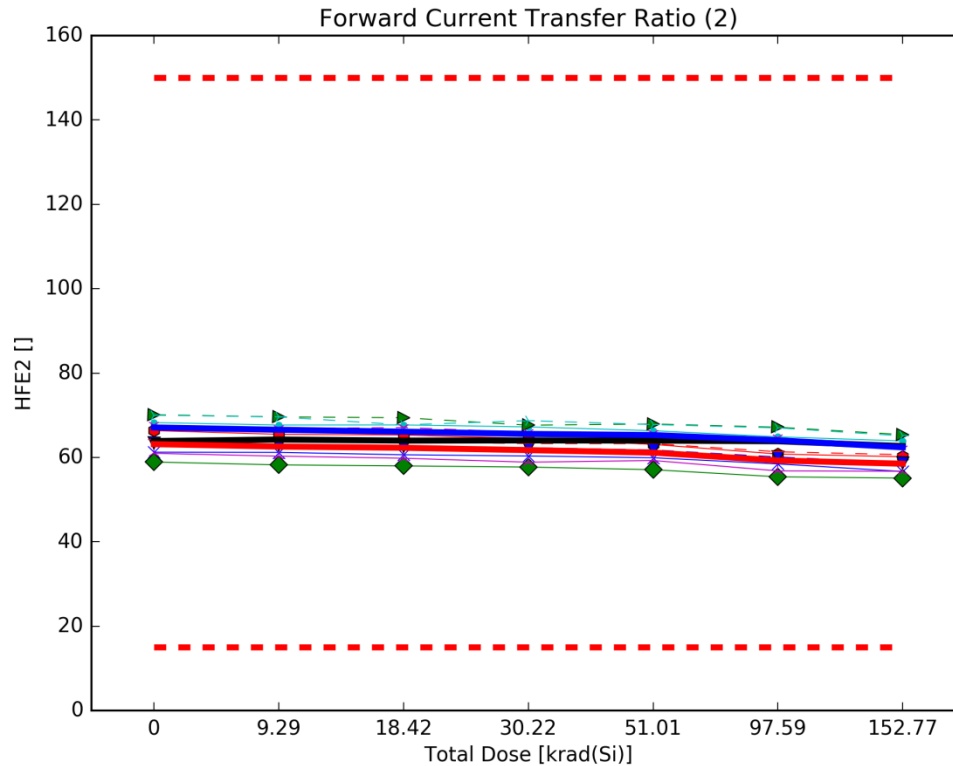
Current transfer ratio (HFE)

BDS16 #1: $V_{CE} = 2V$, $I_C = 0.5 A$



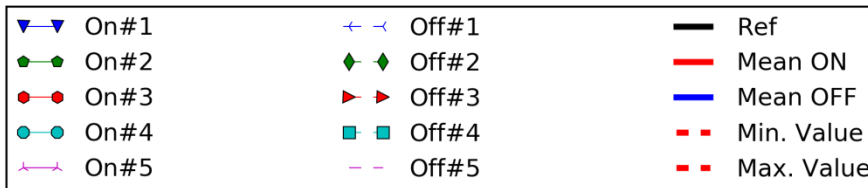
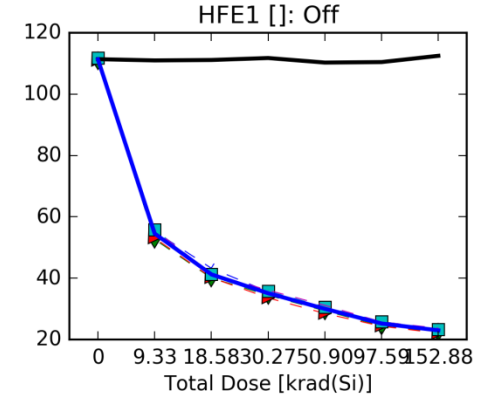
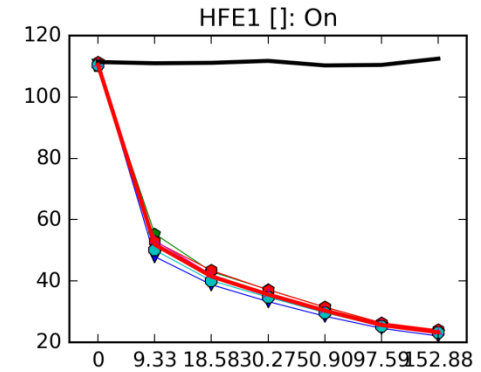
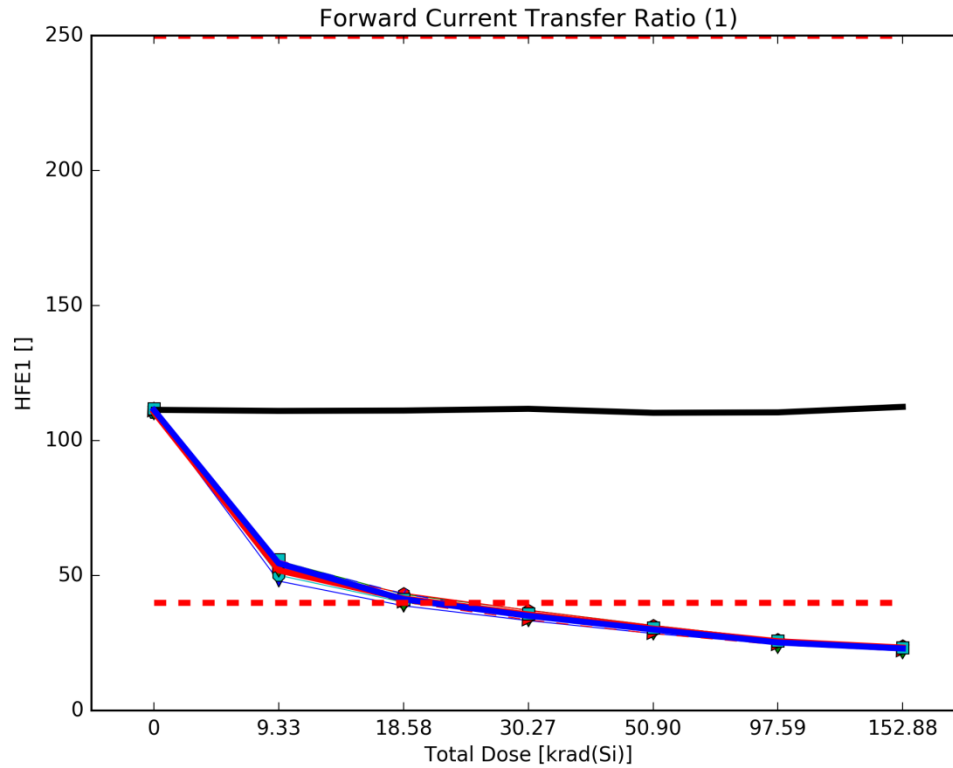
Current transfer ratio (HFE)

BDS16 #2: $V_{CE} = 2V$, $I_C = 4.0 A$



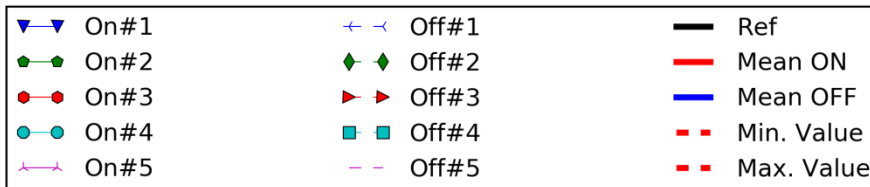
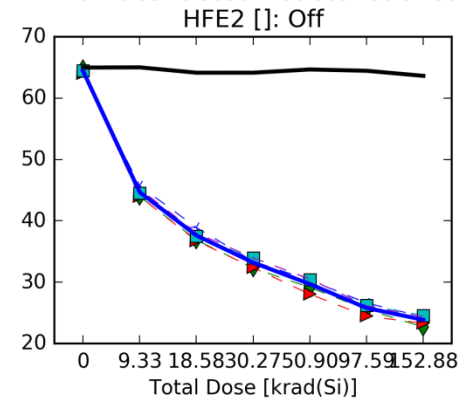
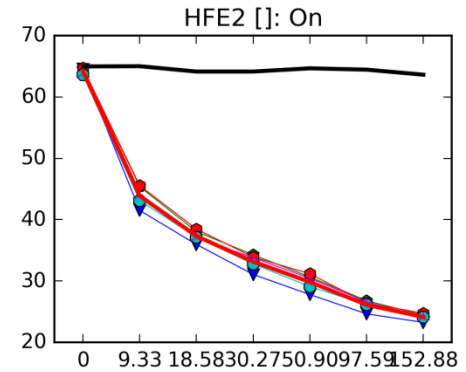
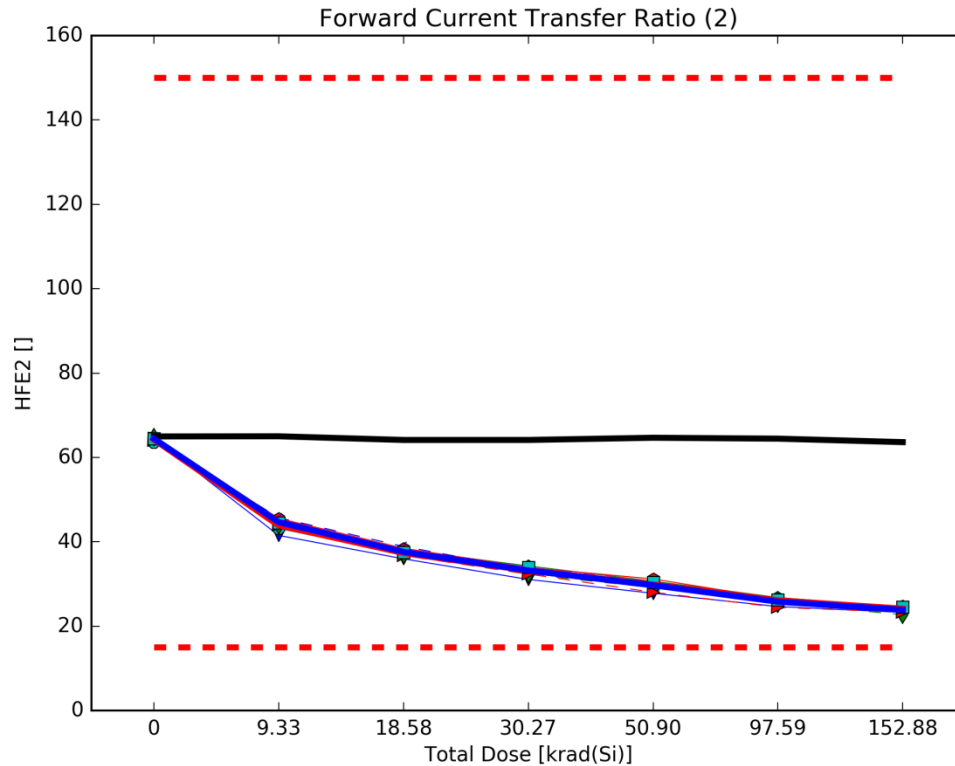
Current transfer ratio (HFE)

BDS18 #1: $V_{CE} = -2V$, $I_C = -0.5 A$



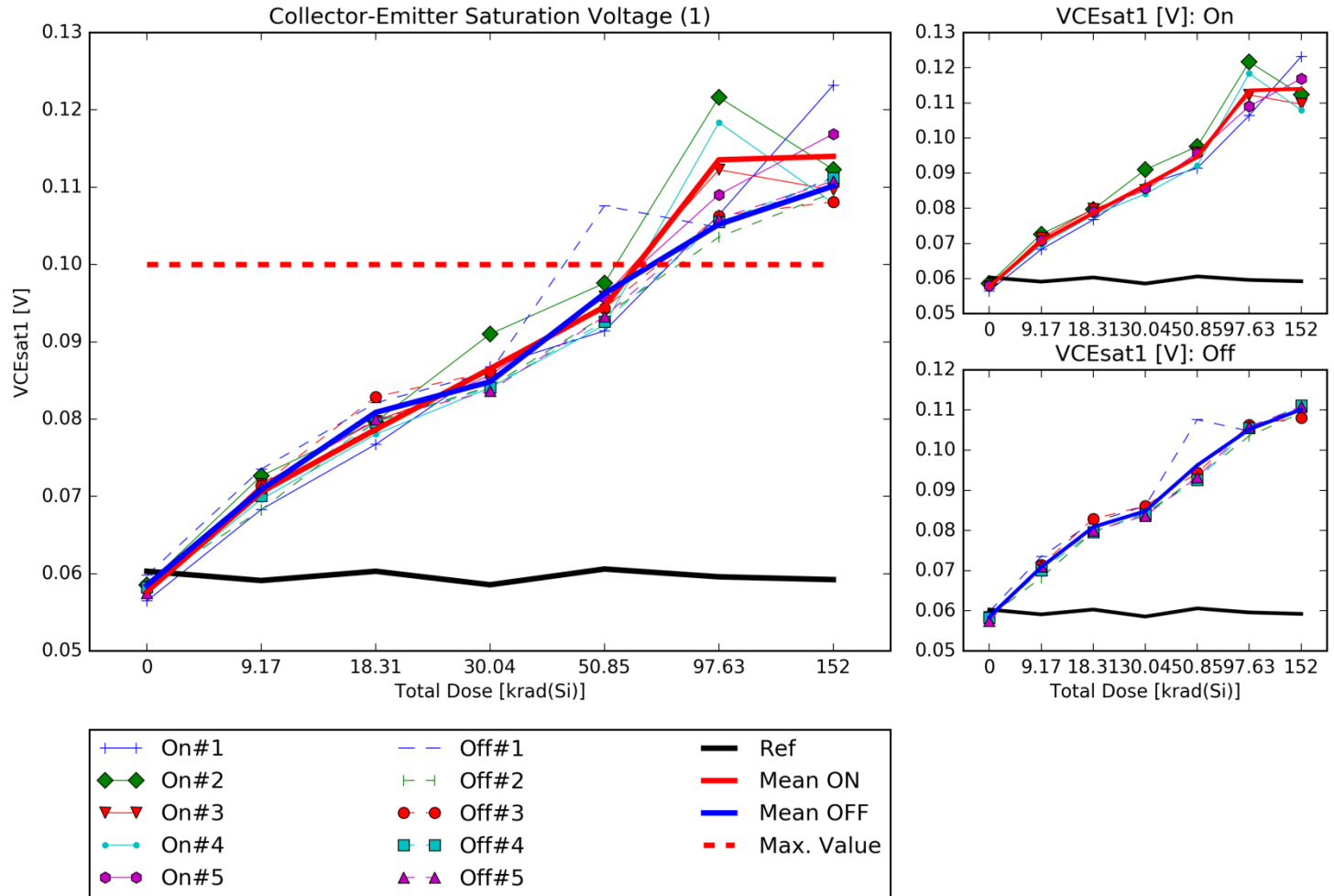
Current transfer ratio (HFE)

BDS18 #1: $V_{CE} = -2V$, $I_C = -4.0 A$



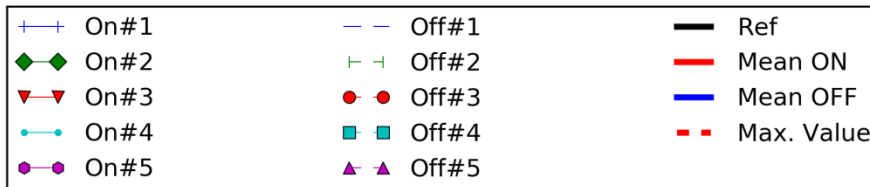
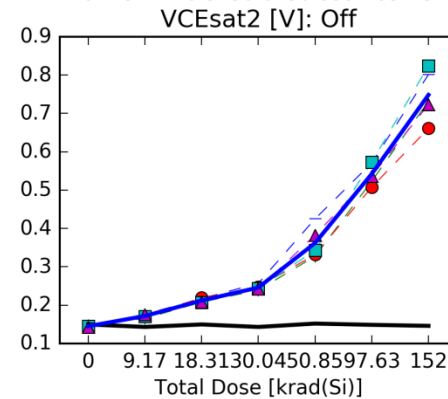
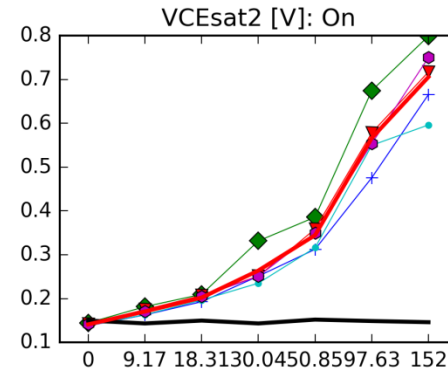
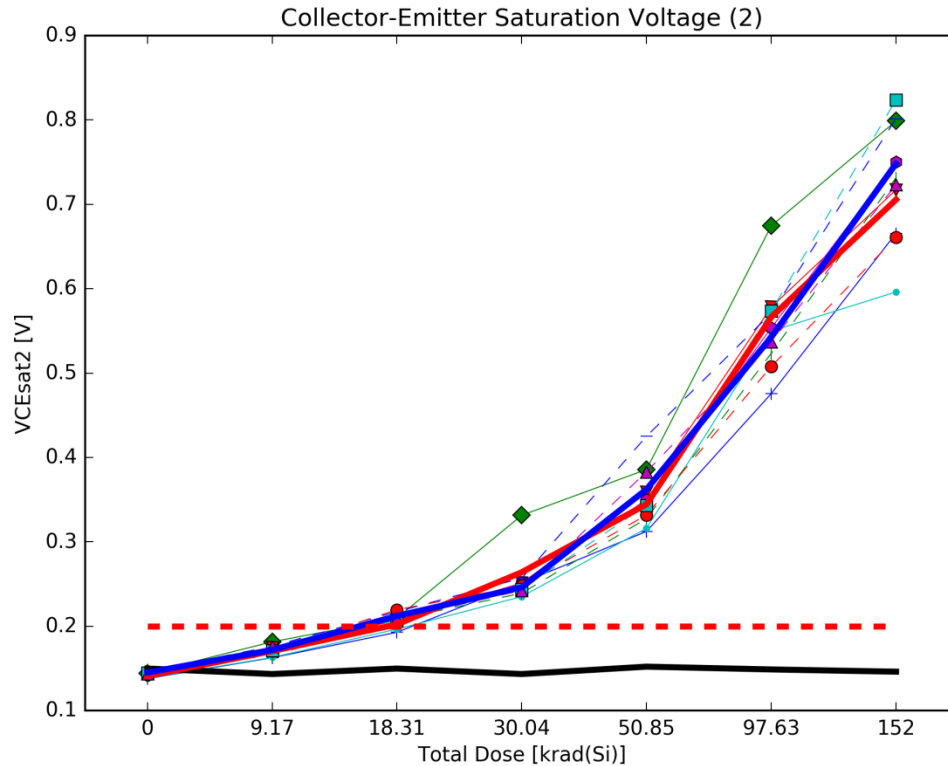
Collector-Emitter Saturation Voltage (VCEsat)

BUL54 #1: $I_C = 100 \text{ mA}$, $I_B = 20 \text{ mA}$



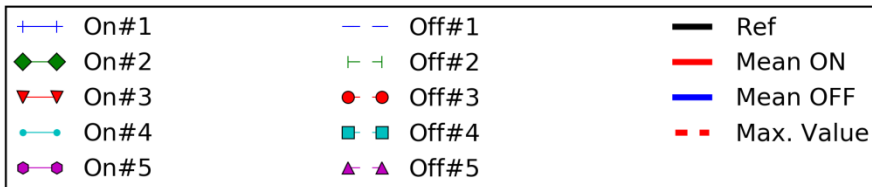
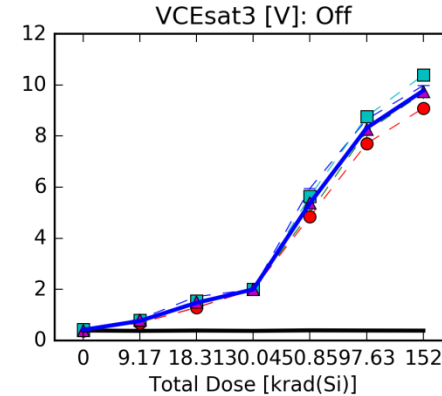
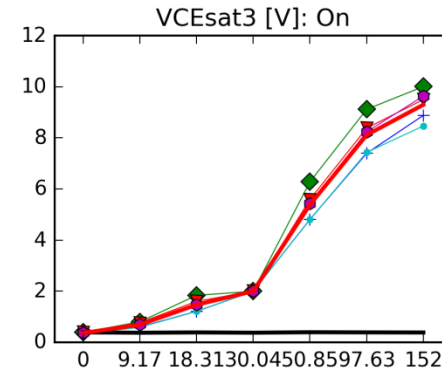
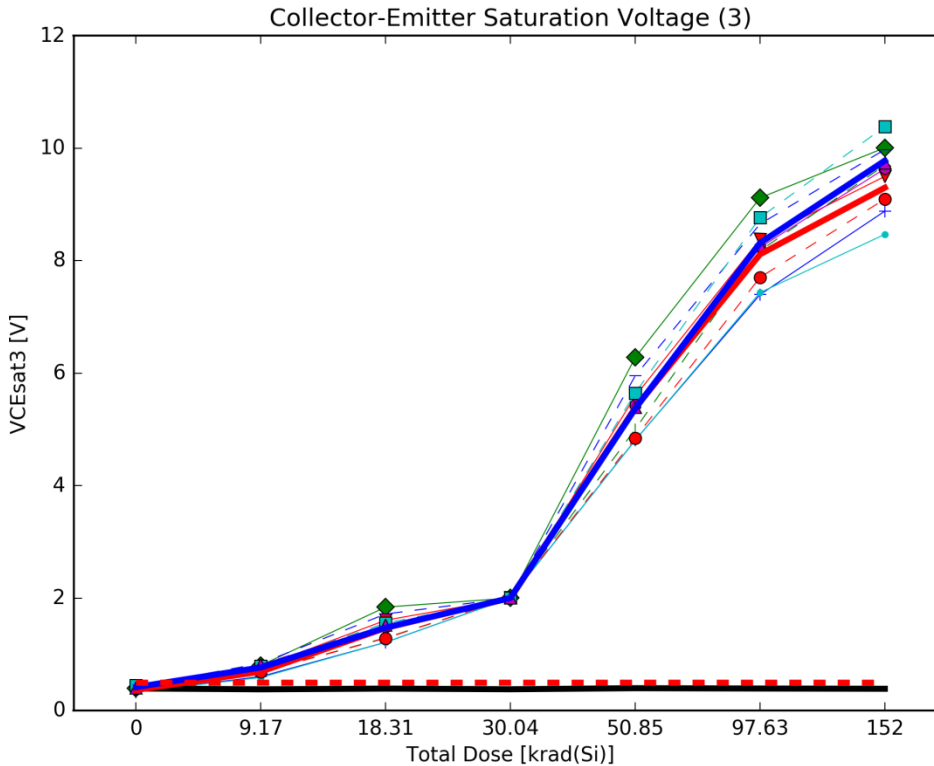
Collector-Emitter Saturation Voltage (VCEsat)

BUL54 #2 $I_C = 0.5 \text{ A}$, $I_B = 0.1 \text{ A}$



Collector-Emitter Saturation Voltage (VCEsat)

BUL54 #3 $I_C = 1.0\text{ A}$, $I_B = 0.2\text{ A}$



Parameter tests

SiC Devices

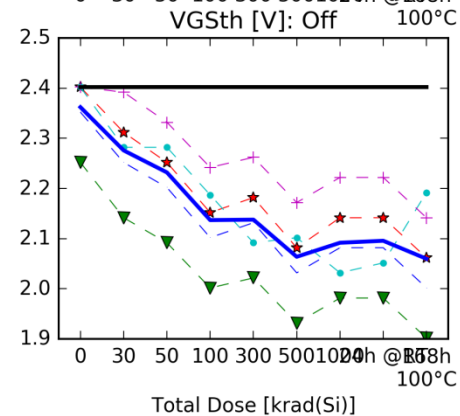
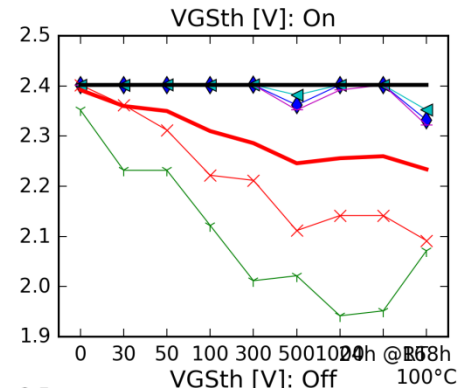
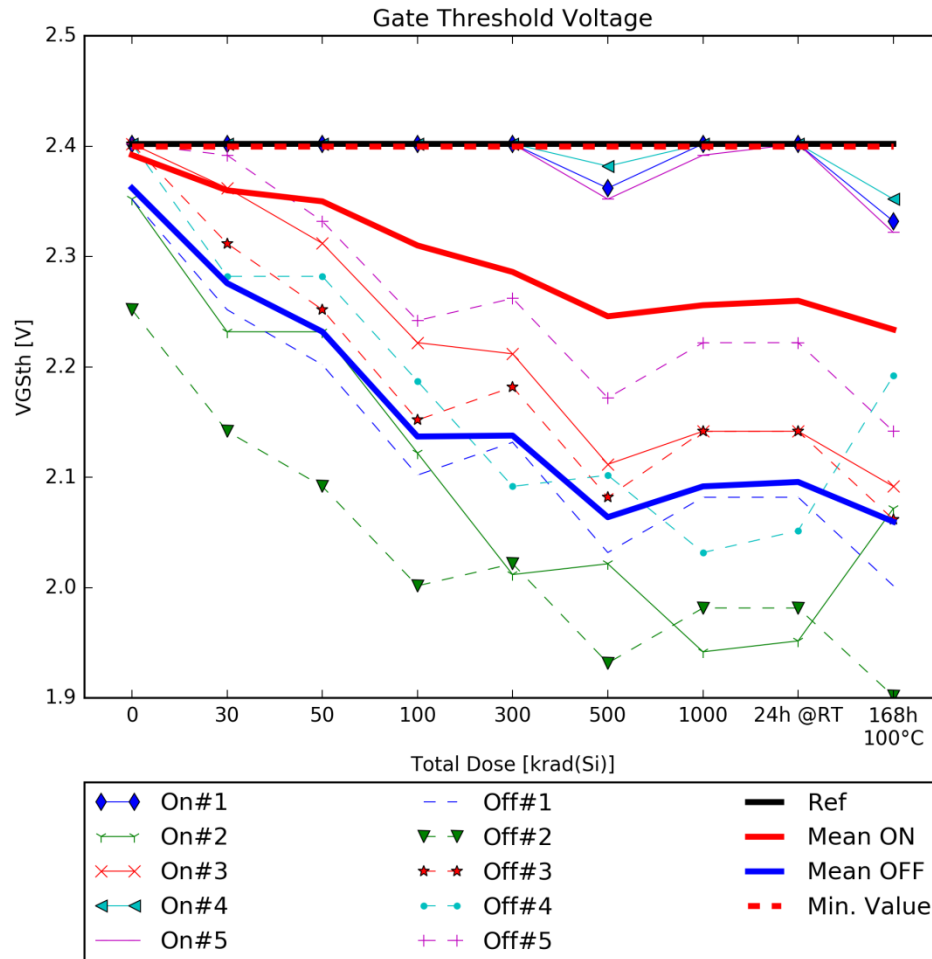
Radiation levels in krad(Si) (Test steps) at which parameters drift out of specs

TM	Test	MOSFET		JFET	Schottky		
		C2M0080120D	SCT20N120	IJW120R100T1	C4D40120D	IDW10G120C5B	SML020DH12
3407	Drain-Source Breakdown Voltage	>1000	>1000	>1000			
3411	Gate-Source Leakage Current	>1000	>1000	>1000			
3413	Zero Gate Voltage Drain Current	>1000	>1000	>1000			
3403	Gate Threshold Voltage	100?	>1000	>1000			
3421	Drain-Source On-State Resistance	>1000	>1000	>1000			
4011	Diode Forward Voltage	>1000	>1000	>1000	>1000	100 - 300	>1000
4016	Reverse Current				>1000	>1000	>1000


 168h @ 100°C currently running

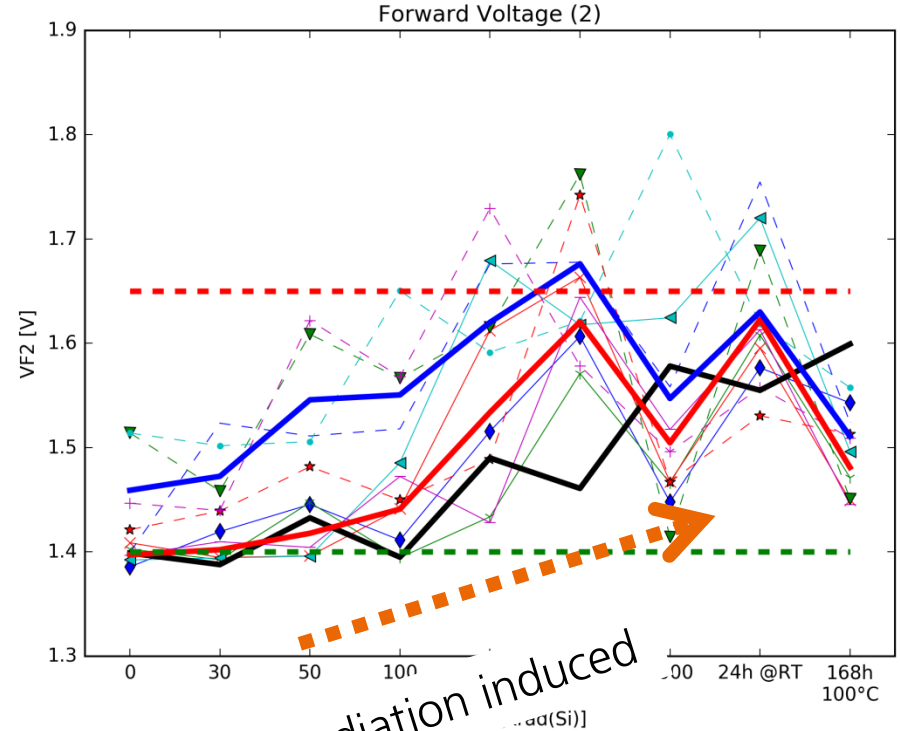
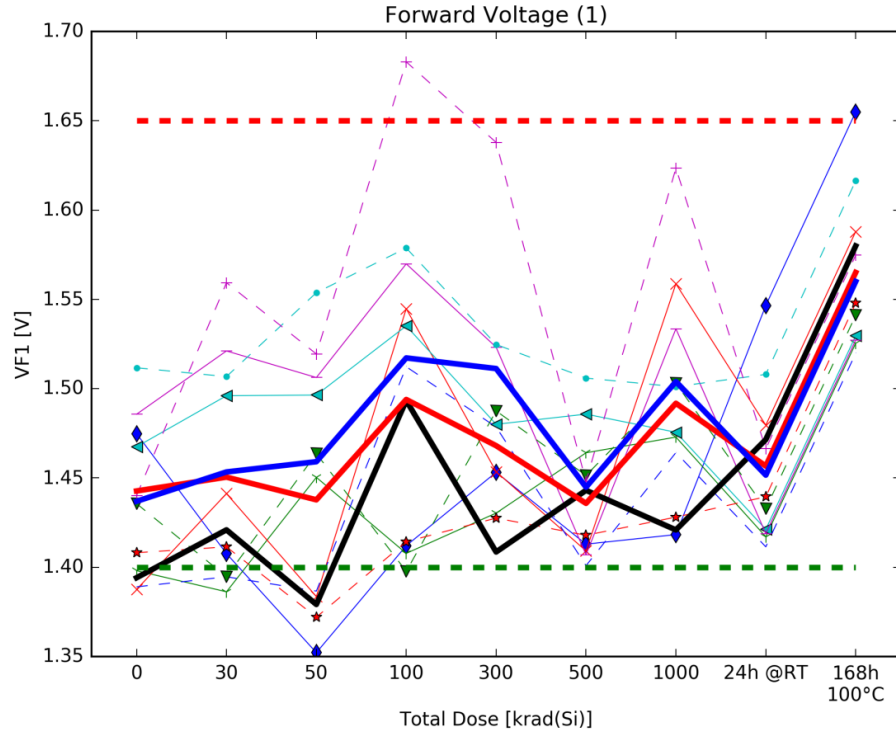
Gate Threshold Voltage ($V_{GS\ th}$)

C2M0080120D: $V_{DS}=10V$, $I_D=5mA$ (Rev.B Datasheet)



Forward Voltage (V_F)

IDW10G120C5B $I_C = 1.0$ A, $I_B = 0.2$ A



Likely other than radiation induced

Summary / Outlook

■ Power Bipolar Transistors

- ELDRS testing ongoing
 - Three candidates with appropriate radiation hardness identified up to 150 krad(Si)
- High dose testing will be performed soon
 - LDR sensitivity enhancement can be checked then

■ SiC power devices

- Co60 testing almost finished
 - 168h @ 100°C ongoing for 2 comp.
 - 4 out of 6 devices passed all tests up to 1 Mrad(Si)
 - 2 remaining parts passed all tests up to 100 krad(Si)
- SEE testing in preparation (approx. June 2017)

Backup

Co60: Accounting for source decay

- Rule of thumb $D(t) = \dot{D}_0 \cdot t$ not applicable (by far)

$$\begin{aligned} D(t_e) &= \int_0^{t_e} \dot{D}_0 \cdot \exp\left(-\ln(2) \cdot \frac{t}{t_{\frac{1}{2}}^{Co60}}\right) dt \\ &= \dot{D}_0 \cdot \frac{t_{\frac{1}{2}}^{Co60}}{\ln(2)} \cdot \left(1 - \exp\left(-\ln(2) \cdot \frac{t_e}{t_{\frac{1}{2}}^{Co60}}\right)\right) \\ \rightarrow t_e &= -\frac{t_{\frac{1}{2}}^{Co60}}{\ln(2)} \cdot \ln\left(1 - \frac{D(t_e)}{\dot{D}_0} \cdot \frac{\ln(2)}{t_{\frac{1}{2}}^{Co60}}\right) \end{aligned}$$